

Title (en)
ELECTRONIC COMPONENT MODULE AND METHOD FOR THE PRODUCTION THEREOF

Title (de)
ELEKTRONISCHES BAUELEMENTMODUL UND VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)
MODULE DE COMPOSANT ÉLECTRONIQUE ET SON PROCÉDÉ DE FABRICATION

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Application
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Abstract (en)
[origin: WO2008064718A1] The invention relates to an electronic component module with at least one multi-layer ceramic circuit carrier (2, 3) and at least one cooling device comprising at least one cooling body (4). A composite layer (5, 6) is arranged at least in some regions between the ceramic circuit carrier (2, 3) and the cooling device (4). Said composite layer is designed for a reactive connection with the ceramic circuit carrier (2, 3) during a primary process and for connection with the cooling device (4). The invention also relates to a method for the production of said electronic component module.

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